PRODUCT ADVANTAGE

High Reliability
Increase Throughput
5X Reflow Cycles
Simplify Assembly Process
Low and High Temperature Curing Options
Filled & Unfilled Options
Good For Miniaturization

OUR THREE PILLARS

1. EXCEEDING PERFORMANCE SPECIFICATIONS
2. MAXIMIZING PRODUCTIVITY
3. LOWERING PROCESS COST

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YINCAE INNOVATION AT ITS BEST

YINCAE Reflowable Underfills
SMT 160 Series

Preferred by global leaders in the electronics manufacturing industry
YINCAE® SMT 160 Series Underfills

YINCAE® has recently developed a reflowable (no - flow) underfill: SMT 160. This material is designed to eliminate capillary underfill, simplify the assembly process, combine soldering and underfilling in SMT processes, and increase throughput.

Reflowable underfills are dispensed or printed onto the board before component placement occurs. The design of the material allows it to remain in place so that component placement can occur in a subsequent step.

These materials are especially helpful for applications with a narrow footprint.

SMT 160 Application Process

1. **Print**
2. **Place Component**
3. **After Reflow**

SMT 160 is a void-free underfill and exhibits no slump when printed.

Contact YINCAE at info@yincae.com for detailed specifications & customization for your specific product requirements.